

Glued SAM data sheet SAM- λ -A- τ -4.0-25.0g-c or SAM- λ -A- τ -4.0-25.0g-e

SAM chip area standard: 4.0 mm x 4.0 mm
 optional: other dimensions on request

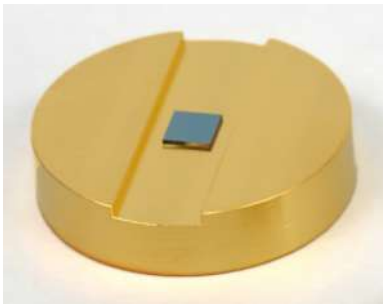
Chip thickness standard: 450 μ m

Front side protection The SAM is protected with a dielectric front layer.

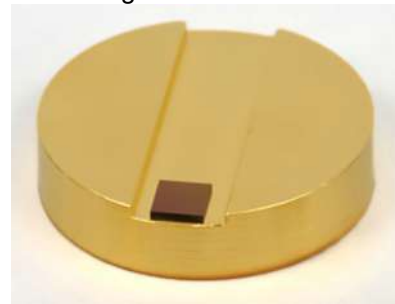
The SAM chip is glued on a gold plated Cu-cylinder with \varnothing 25.0 mm using a thermal conducting adhesive. The adhesive provides a low thermal resistance between the SAM and the mount.

- The **standard** position of the SAM is in the center of the mount \rightarrow x = 4.0-25.0g-c.
- **Optional** the SAM can be soldered at the edge of the mount without extra charges \rightarrow x = 4.0-25.0g-e.

Center mounted SAM



Edge mounted SAM



Dimensions:

